





40V PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

- Ultra-Small Leadless Surface Mount Package
- Complementary NPN Type Available (2DC4617QLP)
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free, "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

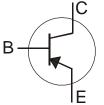
Mechanical Data

- Case: DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0008 grams (approximate)

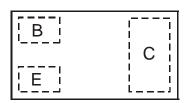








Device Symbol



Top View Device Schematic

Ordering Information (Note 3)

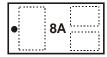
ſ	Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
	2DA1774QLP-7	8A	7	8	3,000
	2DA1774QLP-7B	8A	7	8	10,000

Notes:

- 1. No purposefully added lead.
- 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.
 3. For packaging details, go to our website at http://www.diodes.com.

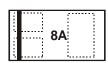
Marking Information

2DA1774QLP-7



Top View Dot Denotes Collector Side

2DA1774QLP-7B



Top View Bar Denotes Base and Emitter Side

8A = Product Type Marking Code



Maximum Ratings @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-50	V
Collector-Emitter Voltage	V_{CEO}	-40	V
Emitter-Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	Ic	-100	mA
Peak Collector Current	I _{CM}	-200	mA

Thermal Characteristics

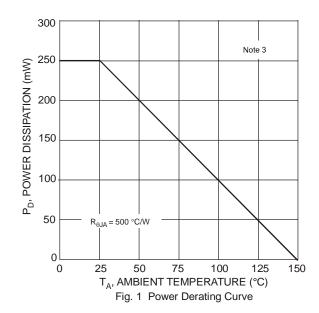
Characteristic	Symbol	Value	Unit
Power Dissipation @T _A = 25°C (Note 4)	P_{D}	250	mW
Thermal Resistance, Junction to Ambient @T _A = 25°C (Note 4)	$R_{ hetaJA}$	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

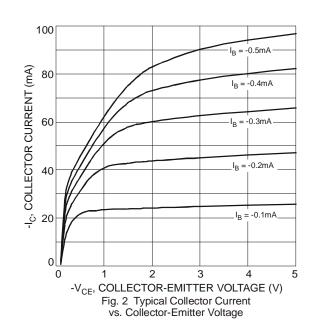
Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)					
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-50	_	V	$I_C = -50\mu A, I_E = 0$
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	-40	_	V	$I_C = -1 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	-5.0	_	V	$I_E = -50\mu A, I_C = 0$
Collector Cutoff Current	I _{CBO}	_	-100	nA	V _{CB} = -30V
Collector Cutoff Current			-5	μΑ	$V_{CB} = -30V, T_A = 150^{\circ}C$
Emitter Cutoff Current	I _{EBO}	_	-100	nA	V _{EB} = -4.0V
ON CHARACTERISTICS (Note 5)					
DC Current Gain	h _{FE}	120	270	_	$V_{CE} = -6.0V, I_{C} = -1.0mA$
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	-0.2	V	$I_C = -50 \text{mA}, I_B = -5.0 \text{mA}$
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C_{obo}	_	5.0	pF	$V_{CB} = -12V$, $f = 1.0MHz$, $I_E = 0$
Current Gain-Bandwidth Product	f⊤	100	_	MHz	$V_{CE} = -12V, I_{C} = -2.0mA,$ f = 100MHz

Notes:

^{5.} Short duration pulse test used to minimize self-heating effect.

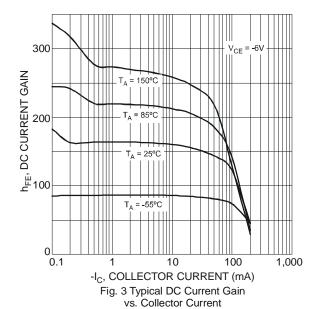


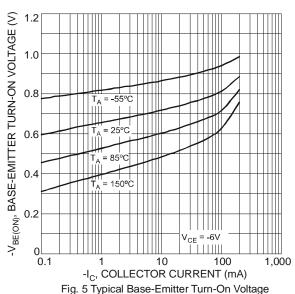


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^{4.} Part mounted on FR-4 PCB with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.







vs. Collector Current

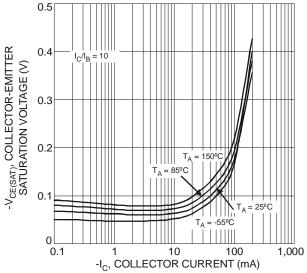


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

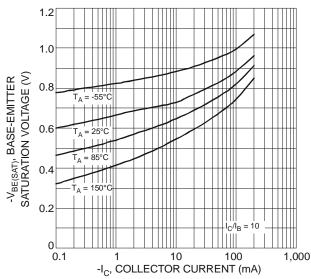
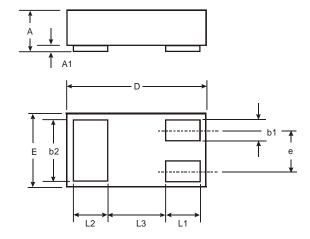


Fig. 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

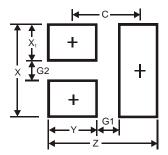
Package Outline Dimensions



DFN1006-3					
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0	0.05	0.03		
b1	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.075	1.00		
Е	0.55	0.675	0.60		
е	_	_	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3		_	0.40		
All	All Dimensions in mm				



Suggested Pad Layout



Dimensions	Value (in mm)	
Z	1.1	
G1	0.3	
G2	0.2	
Х	0.7	
X1	0.25	
Y	0.4	
С	0.7	

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